

ARCSIS ELECTRONIC PACKAGING DAYS 2010

"Flexible Printed Devices"

OCTOBER 7TH & 8TH, 2010, GARDANNE (FRANCE)

CALL FOR PAPERS

Deadline of abstract submission extended to June 30th, 2010

The abstract submission deadline for "Electronic Packaging Days" has been postponed until June 30th 2010. We hope this extra time will encourage more of you to consider participating.

In order to adopt a leading edge position on the microelectronics and packaging activities, ARCSIS has chosen this year to focus its "Electronic Packaging Days", former "Micropackaging Days", on "Flexible printed devices".

This meeting aims to bring together industrials and researchers coming from all Europe and willing to share their expertise and innovations in the field. Participants see in this conference a real opportunity for exchanges with regional and European players.

The event will take place on **October 7th & 8th 2010** at the **Provence Microelectronics Centre in Gardanne**. It will consist of scientific and technical conferences presented by experts from Universities, research centres and industry working in the field of "Flexible printed devices".

OBJECTIVES

Building on its experience of eight years, the meeting is strongly attached to offer its attendees presentations of high quality in a convivial atmosphere.

It provides the opportunity for participants to:

- become familiar with the most recent technical advances in electronic packaging covering both fundamental and applied aspects of the field,
- identify the needs of industry in diverse applications ranging from micro-systems to large area devices,
- share information and discuss the latest research results in an informal atmosphere,
- make new connections and open new prospects for partnership.

LOCATION OF THE EVENT

This Meeting will be hosted by the **Provence Microelectronics Centre in Gardanne**, a brand education and research centre.



This meeting is supported by "Micro-PackS", the first R&D platform for Micropackaging in France, integrating security concerns.

"Micro-PackS", hosted by the Provence Microelectronics Centre, gathers public laboratories and private companies to stimulate the innovations concerning Contactless, flexible packaging and tamper resistance.

"Micro-PackS is supported by ARCSIS in the frame of the competitiveness cluster "Secured Communication Solutions".



It is located at the heart of a major Microelectronics cluster in France gathering leading manufacturers of semiconductor devices and smart cards. It is also 20 km from Aix en Provence, which is a city of art and culture. Moreover, it is an ideal base for visiting the rest of Provence. For further information about Provence: www.visitprovence.com

THEMES

Oral presentations will last 25mn including 10mn for questions and will address the general themes of **Flexible Printed Devices** focusing on the following topics:

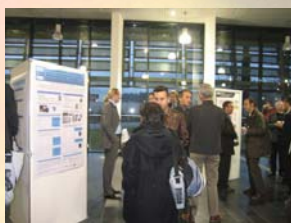
- Wireless autonomous transducers
- Sensors
- Microsources and energy recycling
- MEMS and touch pads
- Microdisplay
- Counting and localization
- Antenna HF and UHF
- Large area electronics
- Green packaging

This workshop will cover the materials, process, design and test fields dedicated to flexible printed devices, without forgetting green packaging and recycling aspects.

Authors can come from a broad range of disciplines including equipment manufacturers, materials suppliers, end users and researchers. **Presentations describing actual case studies** would be extremely interesting and submissions of these contributions are encouraged. **Joint presentations by suppliers and users will be appreciated.**

KEY POINTS 2010:

A poster session will be organised to enable PhD students and researchers as well as equipment manufacturers to present their data and products.



The Keynote speaker, **Philippe Calzi, Technical Director for Products and Marketing with Nexcis Photovoltaic Technology** will make us benefit from his strong skills in electronics and microelectronics and from his successful experiences, particularly within STMicroelectronics and most recently Smart Card Products General Manager. His presentation will deal with **evolutions in photovoltaic technology** with a specific focus on **lightweight and flexible products.**

INSTRUCTIONS FOR PAPER SUBMISSION

Abstracts to be considered for presentation must include a title, the authors' names, their affiliation and a one page summary. **We invite you to precise whether you prefer to present an oral presentation or a poster.**

English will be used for all conferences and documents.

The deadline for abstract submission is Wednesday, June 30th, 2010. Authors will be notified of acceptance of their papers by **Monday, July 19th, 2010.** For your information, workshop fees (proceedings and lunches) for speakers are paid by ARCSIS.

SCIENTIFIC STEERING COMMITTEE

B. Dubois, **Gemalto:**

beatrice.dubois@gemalto.com

P. Collot, **Provence Microelectronics Centre:**

collot@emse.fr

M. Thomas, **CIM PACA Micro-PackS Platform:**

michel.thomas@arcsis.org

P. Dessaux, **NBS Technologies:**

pdessaux@nbstech.com

M. Zafrany, **SPS:** michael.zafrany@s-p-s.com

CONTACT

Corinne JOACHIM

Communication Manager

ARCSIS : Place Paul Borde – BP 19

13790 Rousset - France

Tel: +33 (0)4 42 53 81 50

Fax: +33 (0)4 42 53 81 51

Email: contact@arcsis.org

Website: www.arcsis.org

